

Electronic Patent Application Fee Transmittal

Application Number:	10511566			
Filing Date:	13-Apr-2005			
Title of Invention:	PROCESS OF VAPOR DEPOSITING GLASS LAYERS FOR WAFER-LEVEL HERMETIC ENCAPSULATION OF ELECTRONIC MODULES			
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Attorney Docket Number:	2133.063USU			
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
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Claims:				
Miscellaneous-Filing:				
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Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1510	1510
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Total in USD (\$)				1810